

# GSM2309KP

## 30V P-Channel Enhancement Mode MOSFET

### Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

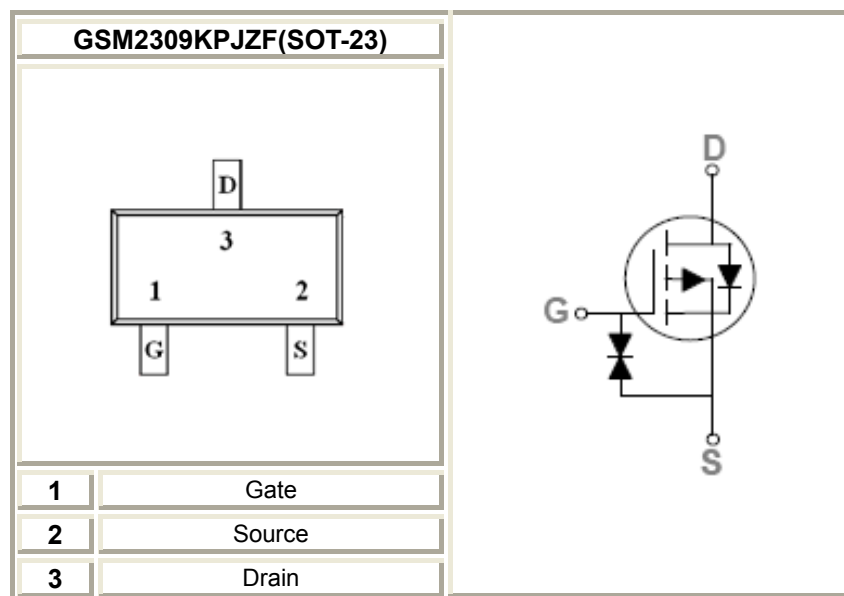
### Features

- -30V, -3.8A,  $R_{DS(ON)}=75m\Omega@V_{GS}=-10V$
- Fast switching
- Suit for -4.5V Gate Drive Applications
- G-S ESD Protection Diode Embedded
- Green Device Available
- SOT-23 package design

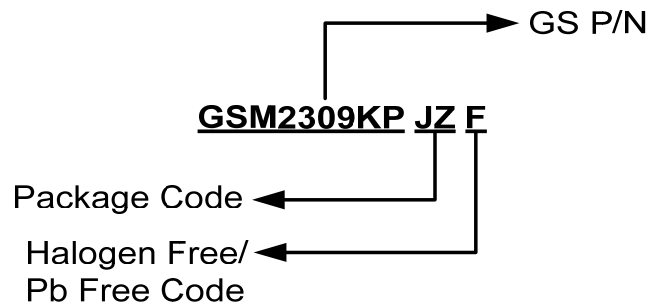
### Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

### Packages & Pin Assignments

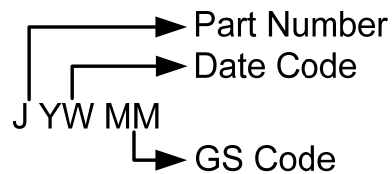


## Ordering Information



Part Number	Package	Quantity Reel
GSM2309KPJZF	SOT-23	3000 PCS

## Marking Information



## Absolute Maximum Ratings

(T<sub>A</sub>=25°C unless otherwise noted)

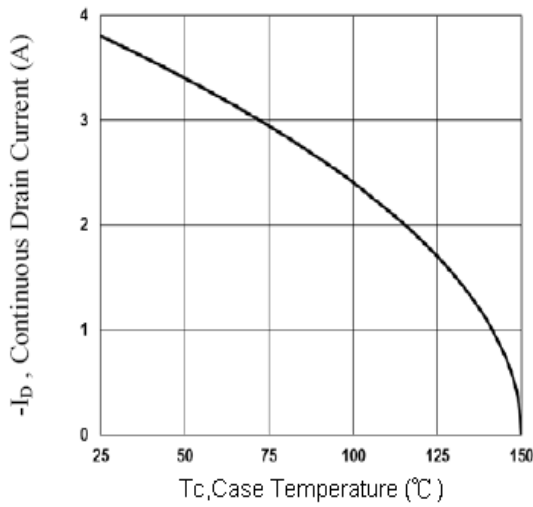
Symbol	Parameter	Typical	Unit	
V <sub>DS</sub>	Drain-Source Voltage	-30	V	
V <sub>GS</sub>	Gate-Source Voltage	±25	V	
I <sub>D</sub>	Continuous Drain Current(T <sub>J</sub> =150°C)	T <sub>A</sub> =25°C	-3.8	A
		T <sub>A</sub> =100°C	-2.4	
I <sub>DM</sub>	Pulsed Drain Current	-15.2	A	
P <sub>D</sub>	Power Dissipation	1.56	W	
T <sub>J</sub>	Operating Junction Temperature Range	-55 to +150	°C	
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C	
R <sub>θJA</sub>	Thermal Resistance-Junction to Ambient	80	°C/ W	

## Electrical Characteristics

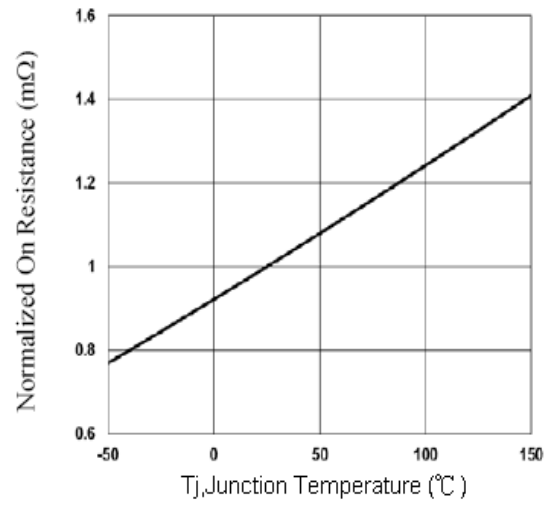
(T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-30			V
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-1.2	-1.6	-2.2	
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA		4		mV/°C
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±25V			±20	uA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V			-1	uA
		V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C			-10	
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current			-3.8	A
I <sub>SM</sub>	Pulsed Source Current				-15.2	
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-3A		64	75	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2A		105	130	
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-10V, I <sub>D</sub> =-3A		3.5		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V			-1	V
<b>Dynamic</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz		460	665	pF
C <sub>oss</sub>	Output Capacitance			45	65	
C <sub>rss</sub>	Reverse Transfer Capacitance			30	45	
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-15V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A		4.2	6	nC
Q <sub>gs</sub>	Gate-Source Charge			1.9	2.5	
Q <sub>gd</sub>	Gate-Drain Charge			1.4	2	
t <sub>d(on)</sub>	Turn-On Time	V <sub>DD</sub> =-15V, I <sub>D</sub> =-1A, V <sub>GS</sub> =-10V, R <sub>G</sub> =6Ω		2.8	5	ns
T <sub>r</sub>				8.7	17	
t <sub>d(off)</sub>	Turn-Off Time			21.4	41	
T <sub>f</sub>				5.7	11	

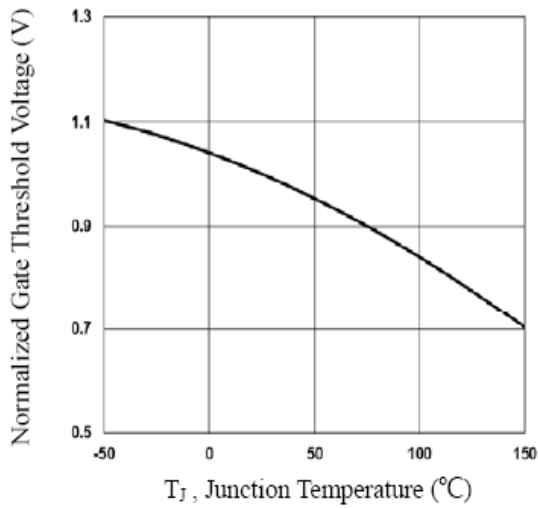
## Typical Performance Characteristics



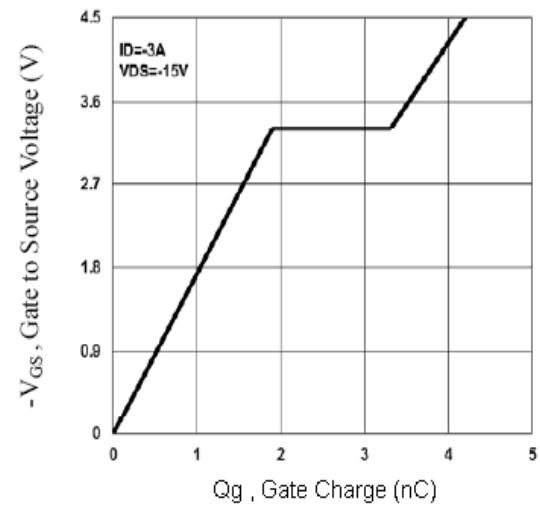
**Fig.1 Continuous Drain Current vs.  $T_c$**



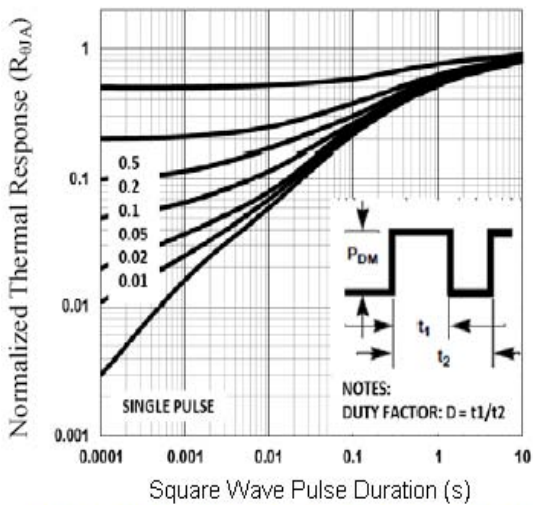
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



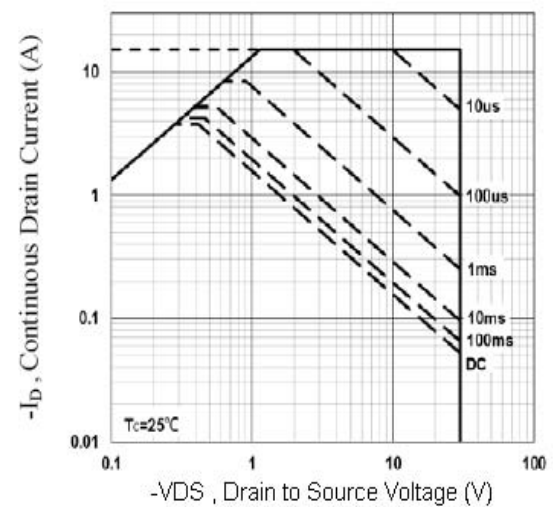
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



**Fig.4 Gate Charge Waveform**



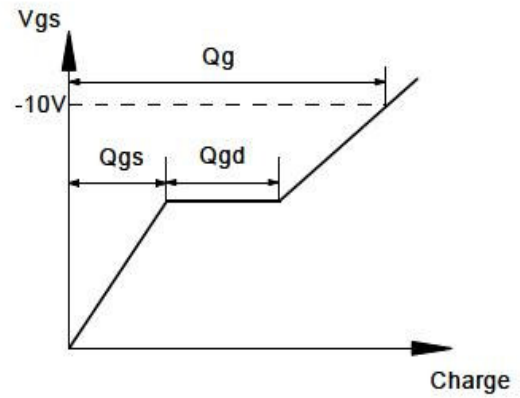
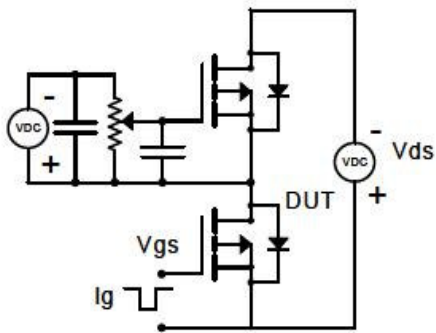
**Fig.5 Normalized Transient Impedance**



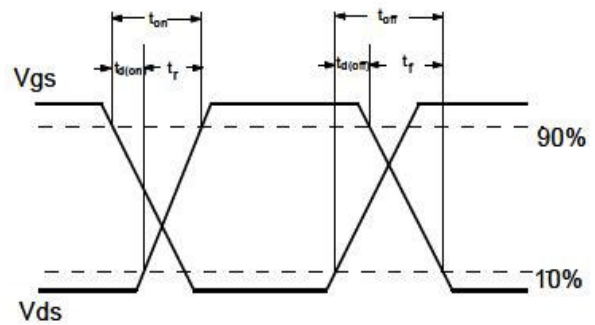
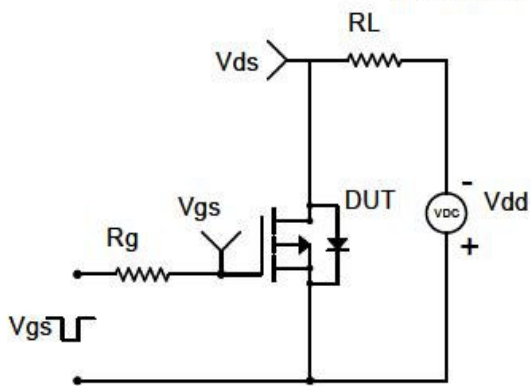
**Fig.6 Maximum Safe Operation Area**

## Typical Characteristics

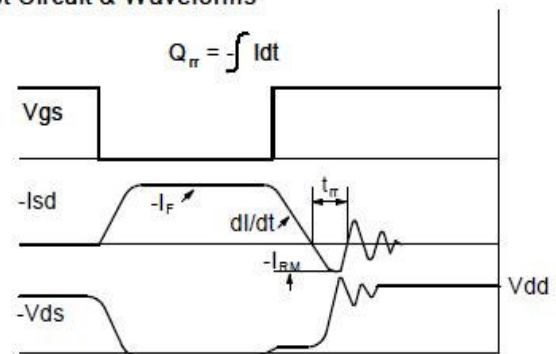
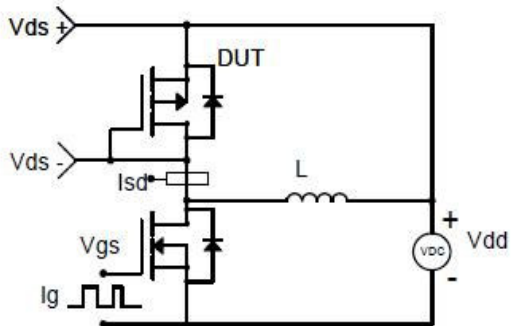
### Gate Charge Test Circuit & Waveform



### Resistive Switching Test Circuit & Waveforms

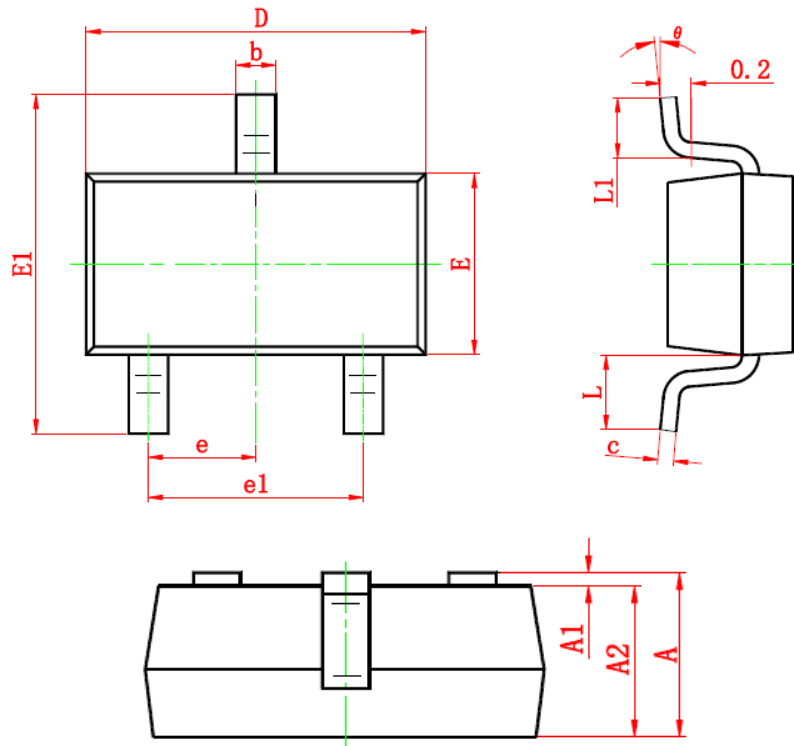


### Diode Recovery Test Circuit & Waveforms



## Package Dimension

### SOT-23







Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.900	1.000	0.035	0.039
A1	0.000	0.100	0.000	0.004
A2	-	0.900	-	0.035
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	6°




## NOTICE

Information furnished is believed to be accurate and reliable. However Globaltech Semiconductor assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties, which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Globaltech Semiconductor. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information without express written approval of Globaltech Semiconductor.



## CONTACT US

GS Headquarter	
	4F.,No.43-1,Lane11,Sec.6,Minquan E.Rd Neihu District Taipei City 114, Taiwan (R.O.C)
	886-2-2657-9980
	886-2-2657-3630
	sales_twn@gs-power.com

Shenzhen Branch(China)	
	1113 B Building, Happiness Washington, Baoan Nan Road, Luohu District, Shenzhen City, China
	0755-22208941
	sales_cn@gs-power.com

RD Division	
	824 Bolton Drive Milpitas. CA. 95035
	1-408-457-0587